

8 7 6 5 4 3 2 1

ENG. NO.

EDP NO.

SIMILAR ITEM

CADFILE NO.

DO NOT SCALE DRAWING

F

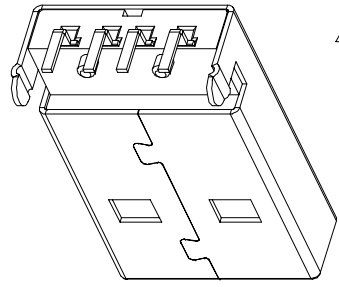
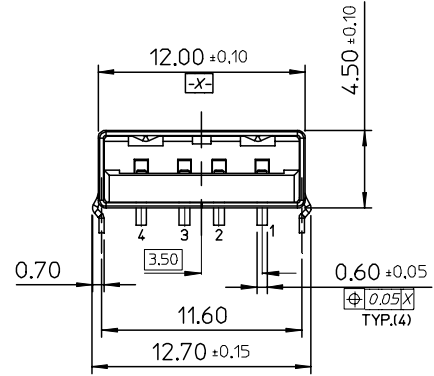
E

D

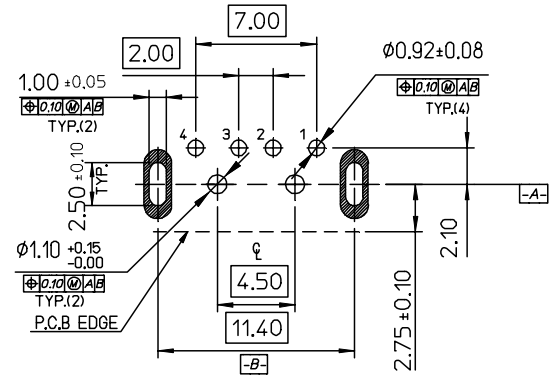
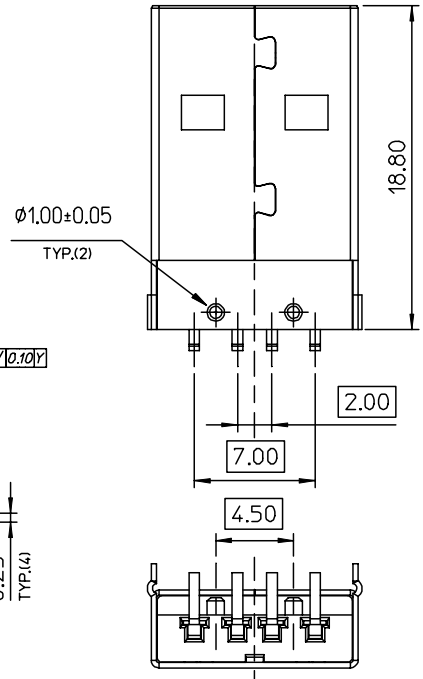
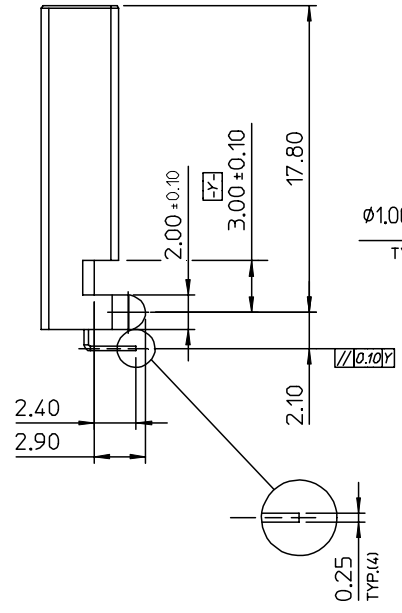
C

B

A



- NOTES:
- MATERIAL:
SHELL: SPCC
HOUSING: THERMOPLASTIC, GLASS FIBER FILLED.
UL 94V-0 RATED.COLOR BLACK.
CONTACT: BRASS
 - PLATING:
TERMINAL:
CONTACT AREA:GOLD(Au)
THICKNESS=30 MICROINCH MINIMUM.
SOLDER TAIL:TIN (Sn), ALLOY,
THICKNESS=120 MICROINCH MINIMUM.
UNDER PLATED:NICKEL(Ni),THICKNESS=50 MICROINCH MINIMUM.
METAL SHELL:
NICKEL(Ni),THICKNESS=120 MICROINCH MINIMUM.
UNDER PLATE: COPPER(Cu), THICKNESS=50 MICROINCH MINIMUM.
 - RECOMMENDED PCB THICKNESS:1.20~1.60mm
 - PRODUCT SPECIFICATION:REFER TO PS-48037-001
 - PACKAGE SPECIFICATION:SEE TABLE
 - TEST SUMMARY :REFER TO TS-48037-001



RECOMMENDED PCB LAYOUT

48037-0001	TRAY	PK-48037-001	
MOLEX P/N	PACKAGE	PACKAGE SPEC.	REMARK
DIMENSIONS:			
<input type="checkbox"/> mm	<input type="checkbox"/> INCH	<input checked="" type="checkbox"/> mm	<input type="checkbox"/> ONLY
<input type="checkbox"/> THIRD ANGLE	<input type="checkbox"/> PROJECTION	SHT	REV
REVISE ON CAD ONLY			

UPDATE PLATING SPEC. EC NO.SH2005-0163 DRWN: KEVIN CHANG CHK: SAM SHIN APPR: ERICK LAN	RTM EC NO.T2004-0067 DRWN: KEVIN CHANG CHK: SAM SHIN APPR: ERICK LAN	DESCRIPTION	QUALITY SYMBOLS MAJOR ▲ +0 CRITICAL ▼ -0
C	B	REV	

GENERAL TOLERANCES: (UNLESS SPECIFIED)	
mm	INCH
4 PLACES	\ . \ .
3 PLACES	\ . \ .
2 PLACES	±0.25 ±0.010
1 PLACE	±0.25 ±0.010
ANGULAR: ±3°	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

SCALE	DESIGN UNITS <input checked="" type="checkbox"/> mm <input type="checkbox"/> INCH
DRAWN BY & DATE COLIN DUAN 030822	
CHECKED BY & DATE SAM SHIN 030822	
APPROVED BY & DATE ERICK LAN 030822	
CAD FILENAME S480370151.MI	MATERIAL NO. SEE TABLE

TITLE: USB A TYPE PLUG R/A CONNECTOR(DIP)	
MOLEX INCORPORATED	
DRAWING NO. SD-48037-001	SHEET NO. 1 OF 1
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.	
SIZE A3	